

IGBT

Packing specifications for IGBT wafer products

Introduction

This document describes the packing specification for IGBT wafer products include the sawn wafers.

Target Device

IGBT wafer products

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1. Sawn Wafer Packing

1.1 Representative of Sawn Wafer Packing

Renesas ships any sawn wafer products after packing them wrapped with UV Foil and these have been dealt with UV irradiation process. Therefore, UV irradiation process is unnecessary on the customer side.

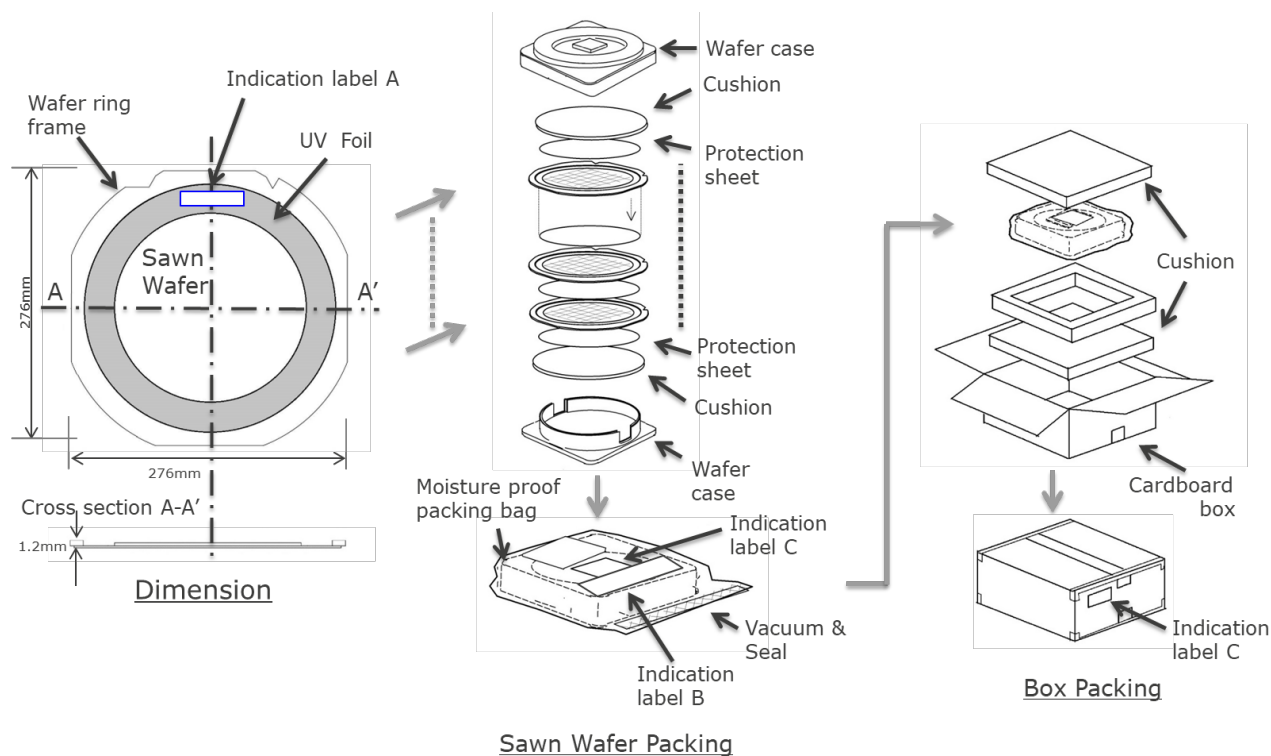


Figure 1-1 Sawn Wafer Packing



Figure 1-2 Sawn wafer Packing photo

1.2 Indication label for Sawn Wafer

Indication labels for Sawn Wafer are shown below.

Regarding the put area of these labels, please refer to P.2 “1.1 Representative of Sawn Wafer Packing”.

(a) Label A

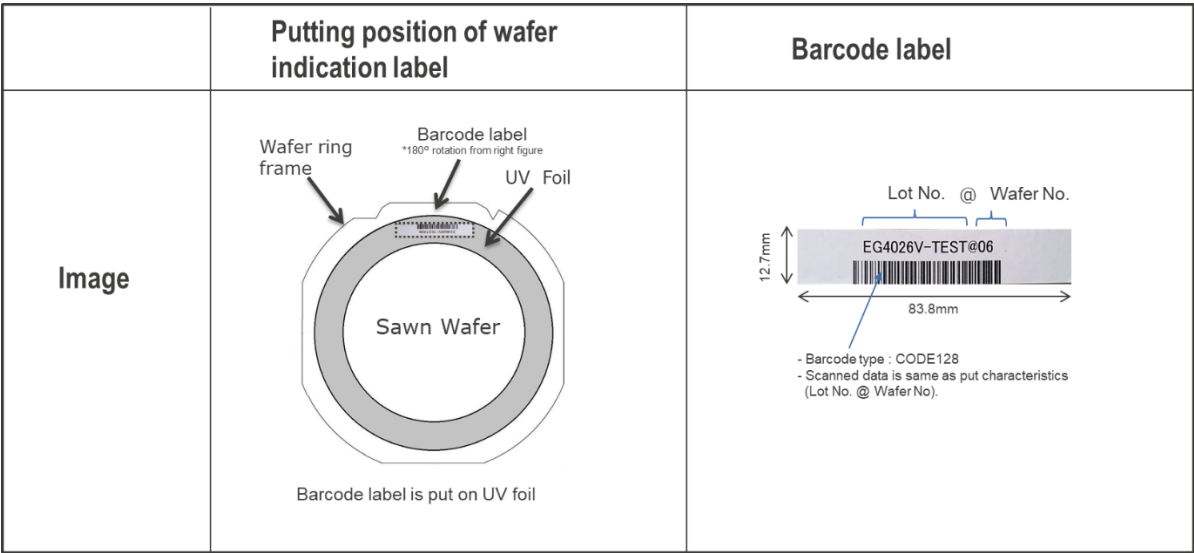


Figure 1-3 Label A

(b) Label B, C

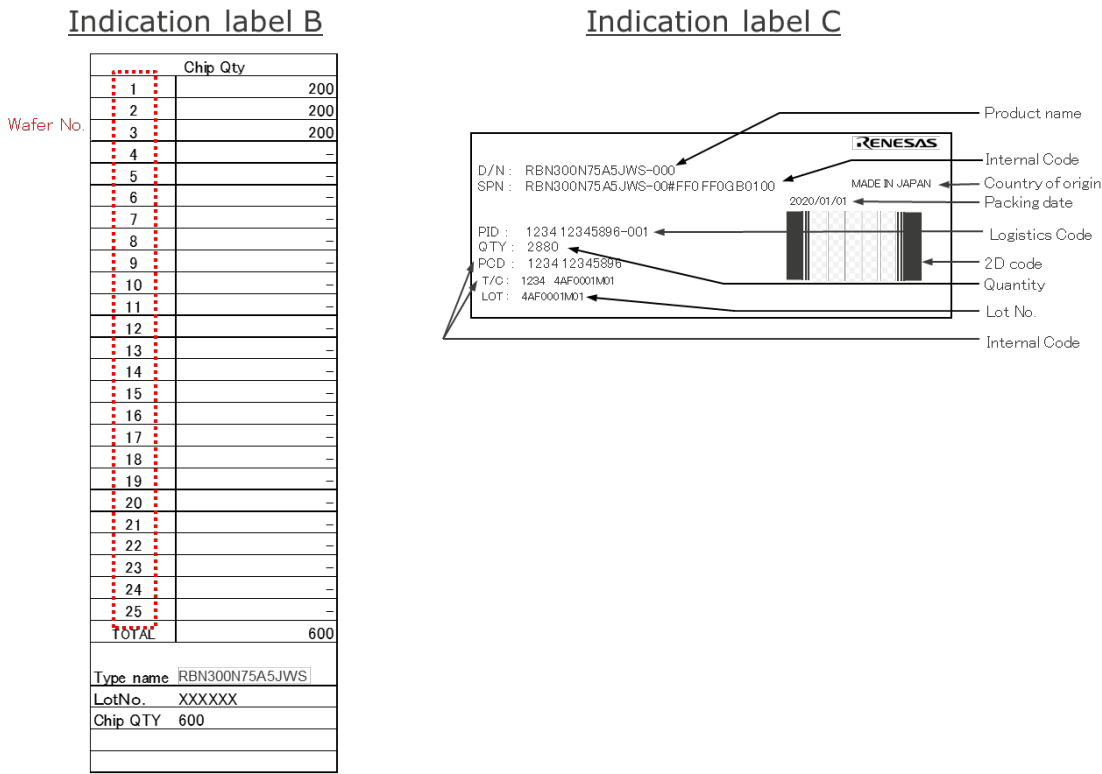


Figure 1-4 Label B, C

1.3 Sawn Wafer Packing Photo

1.3.1 Sawn Wafer Packing Sample 1: Failure marked

8inch Sawn Wafer Packing Sample Failure chips are marked is shown below.

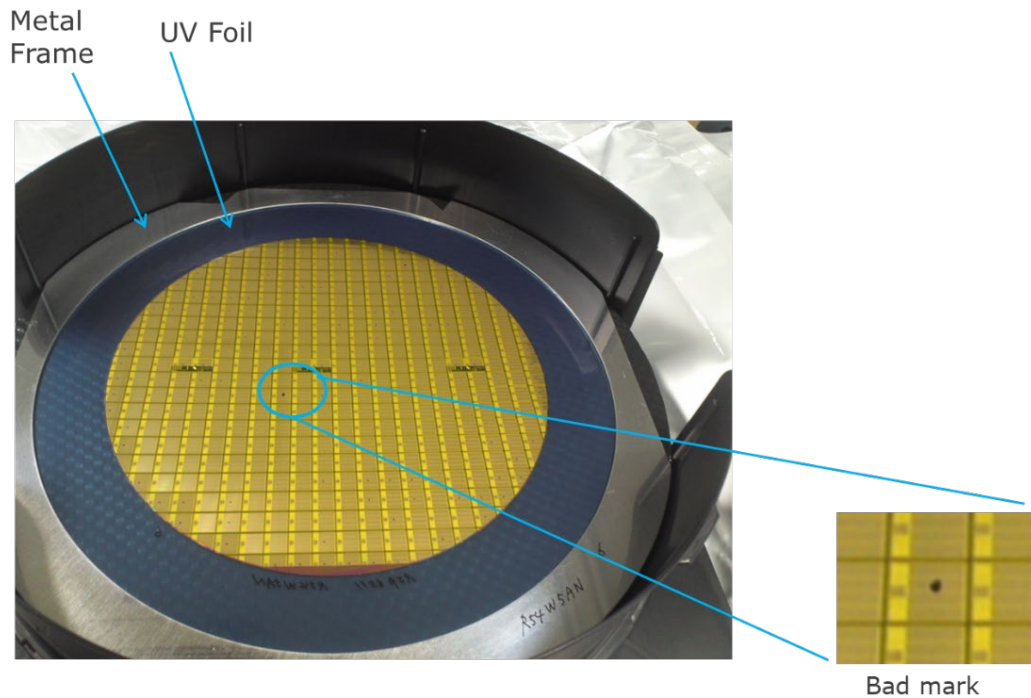


Figure 1-5 8inch Sawn Wafer Packing Sample

1.3.2 Sawn Wafer Packing Sample 2: Inkless

12inch Sawn Wafer sample without marks is shown below.

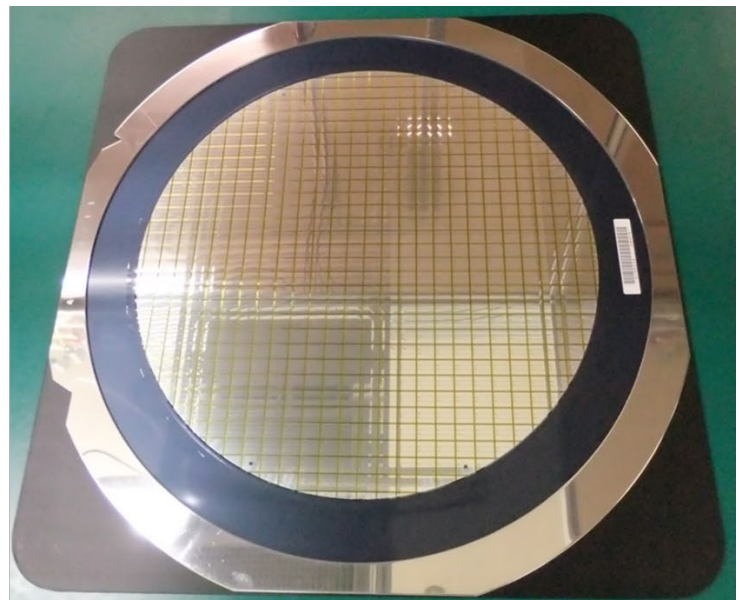
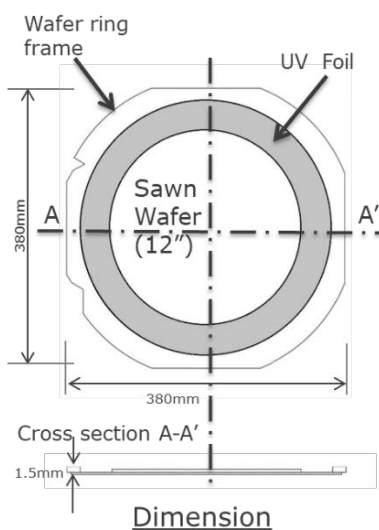


Figure 1-6 Sawn Wafer sample without marks

2. Unsawn Wafer Packing

2.1 Representative of Unsawn Wafer Packing

Renesas ships any unsawn wafer products after packing them. When packing them, the protection sheets are put on the wafers, these are dealt with UV irradiation process and placed with the bottom side of the wafer facing up. Therefore, UV irradiation process is unnecessary on the customer side.

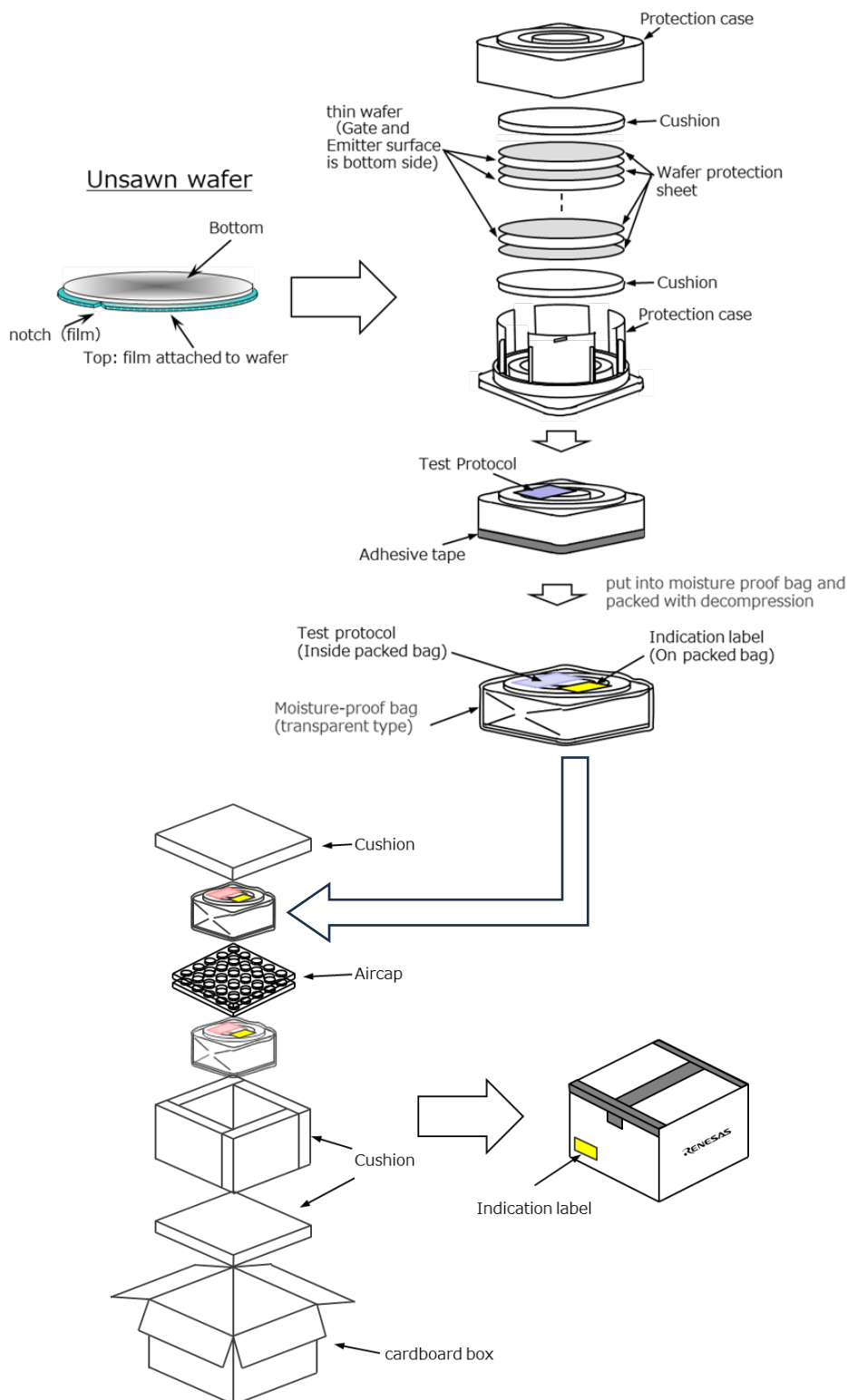


Figure 2-1 Packing specification of Unsawn wafer

2.2 Indication label for Unsawn Wafer

The specification of Indication label for Unsawn Wafer is the same as that for Sawn Wafer.

2.3 Unsawn Wafer Protection case photo

Unsawn Wafer Protection case is shown below.



Figure 2-2 Unsawn Wafer Protection case photo (Left: Body. Right: Cover)

2.4 Laser mark of Unsawn Wafers

On Unsawn wafer, ID number is printed with a laser.

e.g.: BCD12xx – 67

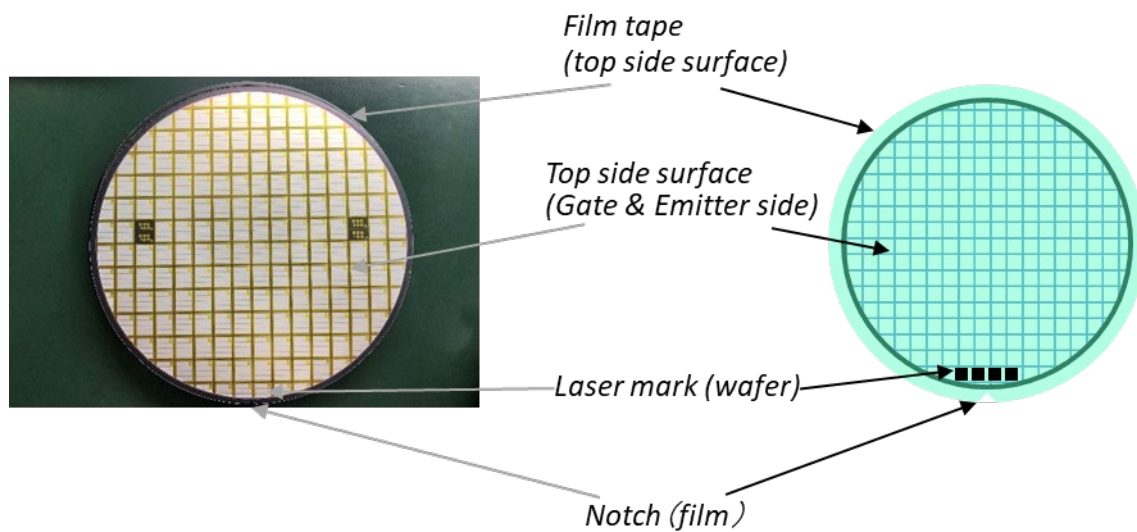


Figure 2-3 layout of the Laser mark for Unsawn Wafer

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jul.29.24	-	First edition

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